



## Tgon™ 800 Series Thermal Interface Material

Tgon™ 800 is a high performance, cost effective thermal interface material.

Tgon 800 is used where electrical isolation is not required. Tgon 800 can be further used where electrical contact along with thermal transfer are desired.

Its unique grain-oriented, plate like structure provides exceptional thermal performance. Tgon 800 can be supplied in 12" x 18" (305 mm x 457 mm) or 18" x 24" (457 mm x 610 mm) sheets, in rolls, or die cut to specific configurations.

Tgon 800 is available with proprietary pressure sensitive adhesive on one side.

This adhesive coating is the thinnest available, thereby minimizing any impact on thermal performance.

Tgon™ 800 sheets are supplied with no liners when ordered without adhesive. With adhesive they are supplied with no top liner and a white release liner on the bottom. Tgon™ 800 is available on rolls and individual die cut shapes.

Item #	Thickness	Density	Tensile Strength	Thermal Conductivity	Thermal Resistance at 100 psi	Thermal Resistance at 681 KPa
Tgon 805	0.005 inches 0.130 mm	2.20 g/cc	650 psi	5.00 W/m-K	0.070 °C-in <sup>2</sup> /W	0.42 °C-cm <sup>2</sup> /W
Tgon 810	0.010 inches 0.250 mm	2.20 g/cc	650 psi	5.00 W/m-K	0.100 °C-in <sup>2</sup> /W	0.66 °C-cm <sup>2</sup> /W
Tgon 820	0.020 inches 0.510 mm	2.20 g/cc	650 psi	5.00 W/m-K	0.170 °C-in <sup>2</sup> /W	1.07 °C-cm <sup>2</sup> /W